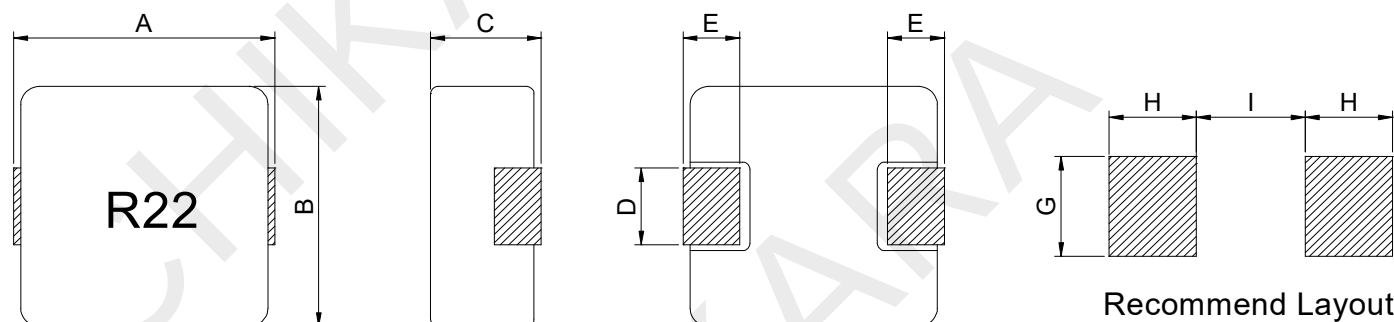


Features

- High energy storage and very low resistance
- Storage temperature range:-55°C to +125°C
- Operating temperature range:-55°C to +125°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:500pcs. Per 13-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



A	B	C	D	E	G	H	I
11.1±0.5	10±0.3	4.0Max.	3.0±0.5	2.0±0.5	4.1	4.1	5.4

Part Number Description

SP15 - 115040 R22 M
 ① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic

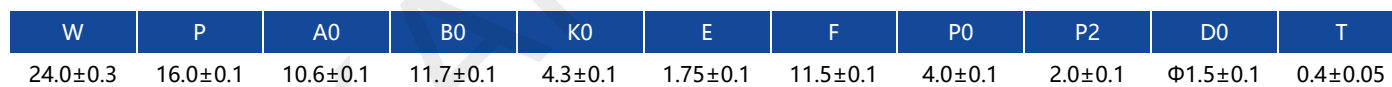


Electrical Characteristic

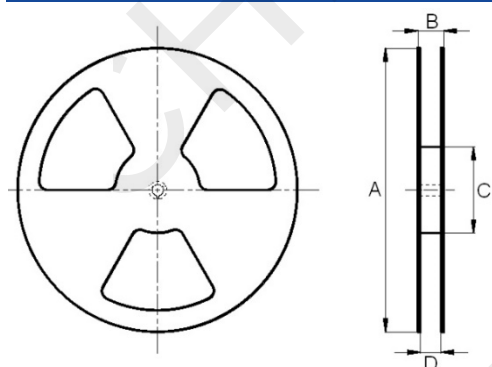
Part Number	Inductance L0(μH)	DCR (mΩ)Typ.	DCR (mΩ)Max.	SRF (MHz)Typ.	Isat (A)Typ.	Irms (A)Typ.
SP15-115040R22M	0.22±20%	0.80	1.00	150	65.0	35.0
SP15-115040R33M	0.33±20%	1.00	1.20	105	62.0	32.0
SP15-115040R36M	0.36±20%	1.05	1.30	100	60.0	31.0
SP15-115040R47M	0.47±20%	1.30	1.50	90	43.0	28.0
SP15-115040R56M	0.56±20%	1.60	1.90	70	40.0	25.0
SP15-115040R68M	0.68±20%	2.40	2.80	55	39.0	22.0
SP15-115040R10M	1.0±20%	3.00	3.40	46	36.0	18.0
SP15-115040R15M	1.5±20%	4.00	4.60	37	33.0	16.0
SP15-115040R22M	2.2±20%	6.50	7.20	30	27.0	12.0
SP15-115040R33M	3.3±20%	10.8	11.8	25	20.0	11.0
SP15-115040R7M	4.7±20%	15.0	16.0	18	17.0	10.0
SP15-115040R6M	5.6±20%	17.0	19.3	16	14.0	9.00
SP15-115040R8M	6.8±20%	18.5	23.3	15	13.5	8.50
SP15-115040R2M	8.2±20%	20.0	24.5	14	12.5	8.00
SP15-115040R100M	10±20%	27.0	32.0	13	12.0	7.50
SP15-115040R150M	15±20%	40.0	45.0	10	10.0	6.25
SP15-115040R220M	22±20%	64.0	74.0	8	7.00	5.00
SP15-115040R330M	33±20%	92.0	112	7	5.00	3.50
SP15-115040R470M	47±20%	145	167	6	4.50	3.00

- Test frequency and voltage:100KHz,1Vrms.
- All test data referenced to 25°C ambient.
- Absolute maximum voltage: 50Vdc.
- Saturation current(Isat) will cause L0 to drop approximately 30%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It' s suggested to verify the temperature rise of the component under the real operation application conditions.

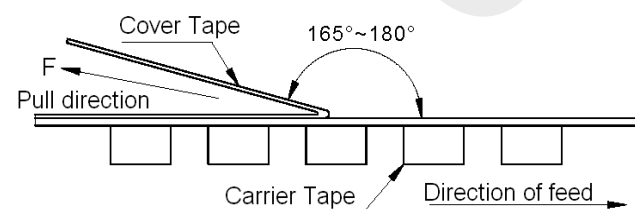
- Carrier Tape (Unit:mm)



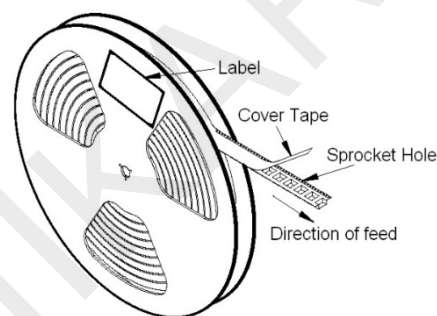
A	B	C	D
$\Phi 330 \pm 1.0$	28.9Max.	$\Phi 100 \pm 1.0$	24.5 ± 0.5



Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.3N	165°~180°	300mm/min.



※ Packing is referred to the international standard IEC 60286-3.



Parts per reel

500Pcs

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.